

Amendments to the Specification:

Please replace paragraph [0003] with the following amended paragraph:

[0003] Speed ~~binning~~binning is usually done based upon some type of broadside test performed by a package tester. These tests are run by the fabrication which saves the information in a database. Due to the limitations of wafer testing, broadside speed testing is usually delayed until the dies are packaged. Thus, it is often difficult to know the speed of a part at wafer test. There are other ring oscillator structures placed on a chip to attempt to compensate for process variation, however, none of them export their information outside of the chip.